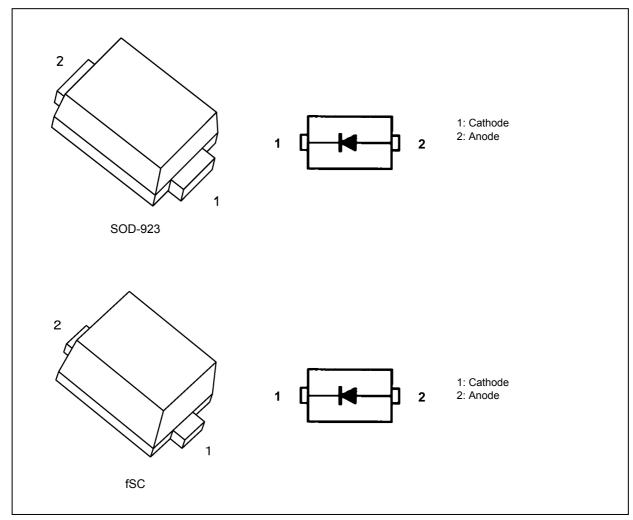
Schottky Barrier Diode Silicon Epitaxial

# 1SS413

### 1. Applications

High-Speed Switching

### 2. Packaging and Internal Circuit



#### 3. Absolute Maximum Ratings (Note) (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	V <sub>RM</sub>		25	V
Reverse voltage	V <sub>R</sub>		20	
Peak forward current	I <sub>FM</sub>		100	mA
Average rectified current	I <sub>O</sub>		50	mA
Power dissipation	PD	(Note 1)	100	mW
Non-repetitive peak forward surge current	I <sub>FSM</sub>	(Note 2)	1	А
Junction temperature	Тј		125	°C
Storage temperature	T <sub>stg</sub>		-55 to 125	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on a glass epoxy circuit board of 20 mm  $\times$  20 mm, Pad dimension of 4 mm  $\times$  4 mm.

Note 2: Measured with a 10 ms pulse.

#### 4. Electrical Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F(1)</sub>	I <sub>F</sub> = 1 mA	_	0.33	_	V
Forward voltage	V <sub>F(2)</sub>	I <sub>F</sub> = 5 mA	_	0.38	_	V
Forward voltage	V <sub>F(3)</sub>	I <sub>F</sub> = 50 mA	_	0.50	0.55	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 20 V	_	_	0.5	μA
Total capacitance	Ct	V <sub>R</sub> = 0 V, f = 1 MHz	_	3.9	_	pF

#### 5. Marking

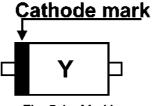


Fig. 5.1 Marking

#### 6. Usage Considerations

• Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.

#### 7. Land Pattern Dimensions (for reference only)

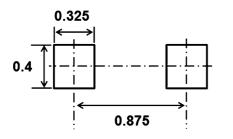


Fig. 7.1 SOD-923 (Unit: mm)

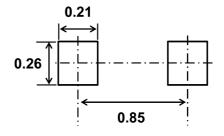
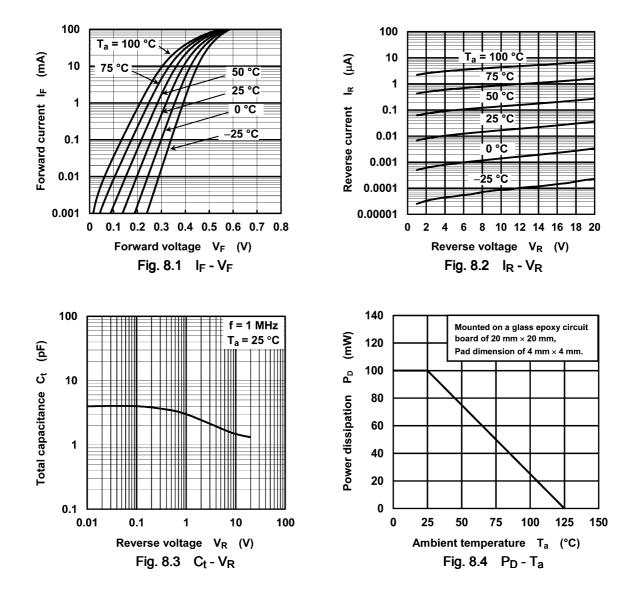


Fig. 7.2 fSC (Unit: mm)

#### 8. Characteristics Curves (Note)



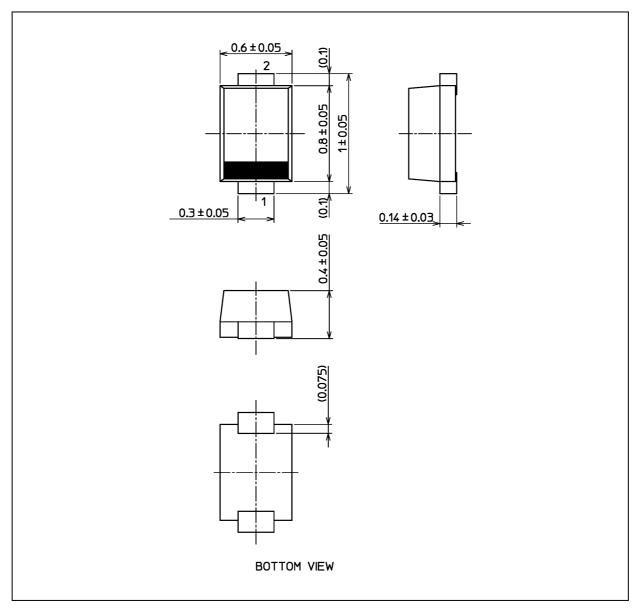
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### Package Dimensions

1SS413

Unit: mm



Weight: 0.55 mg (typ.)

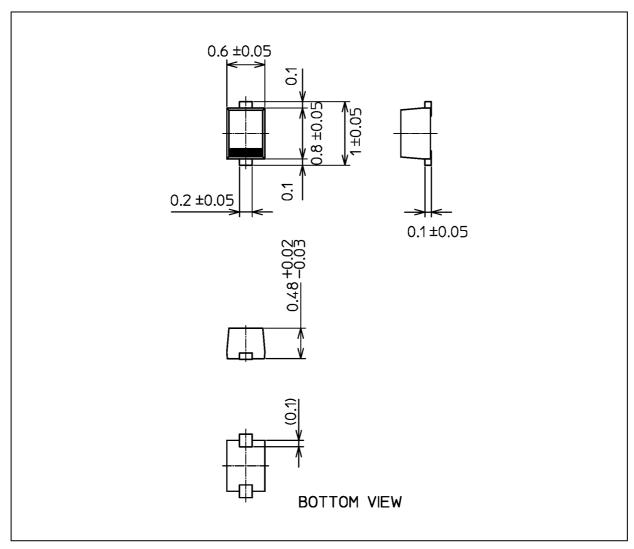
Package Name(s)		
TOSHIBA: 1-1AH1A		
Nickname: SOD-923		



#### Package Dimensions

1SS413

Unit: mm



Weight: 0.6 mg (typ.)

	Package Name(s)
TOSHIBA: 1-1L1S	
Nickname: fSC	

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